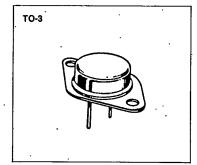
IRF120/121/122/123

N-CHANNEL POWER MOSFETS

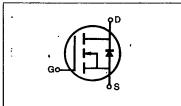
FEATURES

- Low R_{DS(on)}
- Improved inductive ruggedness
- Fast switching times
- Rugged polysilicon gate cell structure
- Low input capacitance
- Extended safe operating area
- Improved high temperature reliability
- TO-3 package (Standard)



PRODUCT SUMMARY

Part Number	V _{DS}	R _{DS(on)}	łp		
IRF120	-100V	0.300	8.0A		
IRF121	60V	0.30Ω	8.0A		
IRF122	100V	0.40Ω	7.0A		
IRF123	60V	0.40Ω	7.0A		



MAXIMUM RATINGS

- Characteristic ·	Symbol	IRF120	IRF121	IRF122	IRF123	Unit		
Drain-Source Voltage (1)	V _{DSS} ·	100	60	100	60	Vdc		
Drain-Gate Voltage (R _{GS} =1.0MΩ)(1)	VDGR	100	. 60	100	. 60	Vdc		
Gate-Source Voltage	V _{GS}	,,,	Vdc					
Continuous Drain Current T _C =25°C	· ID	8.0	8.0	7.0	7.0	Adc		
Continuous Drain Current T _C =100°C	ΙD	5.0	5.0	4.0	4.0	Adc		
Drain Current—Pulsed (3)	I _{DM}	32	32	28	28	Adc		
Gate Current—Pulsed	I _{GM}		Adc					
Total Power Dissipation @ T _C =25°C Derate above 25°C	P _D		Watts W/°C					
Operating and Storage Junction Temperature Range	TJ, Tstg		°C					
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL		300					

Notes: (1) T_J=25°C to 150°C (2) Pulse test: Pulse width≤300μs, Duty Cycle≤2% (3) Repetitive rating: Pulse width limited by max. junction temperature

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N-CHANNEL POWER MOSFETS

IRF120/121/122/123

ELECTRICAL CHARACTERISTICS (Tc=25°C unless otherwise specified)

Characteristic	Symbol	Туре	Min	Тур	Max	Units	: Test Conditions	
Drain-Source Breakdown	BVnss	IRF120 IRF122	100	_	-	v	V _{GS} =0V	
Voltage _.		IRF121 IRF123	60	_	_ '	v	I _D =250μA	
Gate Threshold Voltage	V _{GS(th)}	ALL	2.0	_	4.0	٧	V _{DS} =V _{GS} , I _D =250μA	
Gate-Source Leakage Forward	lass	ALL	-	-	100	nΑ	V _{GS} =20V	
Gate-Source Leakage Reverse	l _{GSS}	ALL	ı	-	-100	nΑ	V _{GS} =-20V	
Zero Gate Voltage	ioss	ALL	_		250	μΑ	V _{DS} =Max. Rating, V _{GS} =0V	
Drain Current	ددن	ALL	_		1000	μΑ	V _{DS} =Max. Rating×0.8, V _{GS} =0V, T _C =125°C	
On-State Drain-Source	In.	IRF120 IRF121	8.0	-	ŀ	A	V _{DS} >I _{D(on)} ×R _{DS(on) max} , V _{GS} =10V	
Current (2)	ID(on)	IRF122 IRF123	7.0	ı	-	A·		
Static Drain-Source On-State		IRF120 IRF121	_	0.23	0.30	Ω	V _{GS} =10V, I _D =4.0A	
Resistance (2)	R _{DS(on)}	IRF122 IRF123	_	0.30	0.40	Ω	1 VGS - 10V, 1D - 4.0A	
Forward Transconductance (2)	gfs.	ALL	1.5	3.1	_	υ	V _{DS} >I _{D(on)} ×R _{DS(on) max.} , I _D =4.0A	
Input Capacitance .	Ciss	ALL	1	460	600	pF ·		
Output Capacitance	Coss	ALL	_	220	400	ρF	V _{GS} =0V, V _{DS} =25V, f=1.0MHz	
Reverse Transfer Capacitance	Crss	ALL	-	70	100	ρF		
Turn-On Delay Time	t _{d(on)}	ALL	_	1	∙40	ns		
Rise Time	tr	ALL	-	-	70	ns	V_{DD} =0.5BV _{DSS} , I_D =4.0A, Z_O =50 Ω	
Turn-Off Delay Time	t _{d(off)}	ALL	ļ	-	100	ns	(MOSFET switching times are essentially independent of operating temperature.)	
Fall Time	tí	ALL	-	_	70	ns		
Total Gate Charge (Gate-Source Plus Gate-Drain)	Q ₉	ALL	_	9.8	15	nC	V _{GS} =10V, I _D =10Å, V _{DS} =0.8 Max. Rating	
Gate-Source Charge	Qgs	ALL	-	3.5		nĆ	(Gate charge is essentially independent of operating temperature.)	
Gate-Drain ("Miller") Charge	Q_{gd}	ALL	_	6.3	_	nC		

THERMAL RESISTANCE

Junction-to-Case	R _{thJC}	ALL	_	_	3.12	K/W	
Case-to-Sink	RthCS	ALL	_	0.1	_	K/W	Mounting surface flat, smooth, and greased
Junction-to-Ambient	RthJA	ALL	_	_	30	K/W	Free Air Operation

Notes: (1) T_J=25°C to 150°C (2) Pulse test: Pulse width≤300µs, Duty Cycle≤2% (3) Repetitive rating: Pulse width limited by max. junction temperature





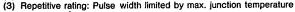
DE 7964142 0005071 4 IRF120/121/122/123

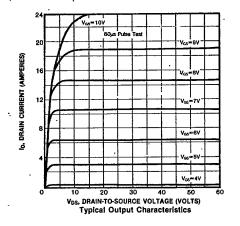
N-CHANNEL POWER MOSFETS

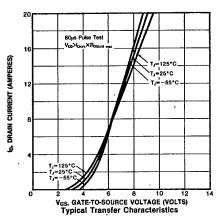
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

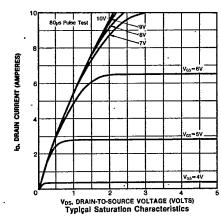
Characteristic	· Symbol	Туре	Min	Тур	Max	Units	Test Conditions	
Continuous Source Current (Body Diode)	Is	IRF120 IRF121	_	_	8.0	· A	•	
	is	IRF122 IRF123	_	-	7.0		Modified MOSFET symbol showing the integral	
Pulse Source Current	Ism	IRF120 IRF121	-	-	32		showing the integral reverse P-N junction rectifier	
(Body Diode) (3)	'SM	IRF122 IRF123	1	1	28	A		
Diode Forward Voltage (2)	Vsp	IRF120 IRF121	_	-	2.5	<	T _C =25°C, I _S =8.0A, V _{GS} =0V	
		IRF122 IRF,123	-	_	2.3	٧	T _C =25°C, I _S =7.0A, V _{GS} =0V	
Reverse Recovery Time	trr	ALL	_	280		ns	T _J =150°C, I _F =8.0A, dI _F /dt=100A/μs	

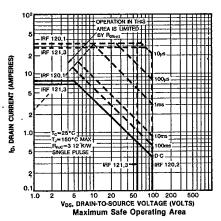
Notes: (1) T_J=25°C to 150°C (2) Pulse test: Pulse width≼300µs, Duty Cycle≤2% (3) Repetitive rating: Pulse width limited by max. junction temperature

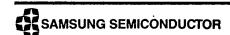












7964142 SAMSUNG SEMICONDUCTOR INC 98D 05072 7964142 0005072 6 **N-CHANNEL** IRF120/121/122/123 **POWER MOSFETS** thic, normalized effective transient thermal impedance (per unit) 11. SQUARE WAVE PULSE DURATION (SECONDS)

Maximum Effective Transient Thermal Impedance Junction-to-Case Vs. Pulse Duration lor, REVERSE DRAIN CURRENT (AMPERES) gfs, TRANSCORDUCTANCE (SIEMENS) V_{SD}, SOURCE-TO-DRAIN VOLTAGE (VOLTS)
Typical Source—Drain Diode Forward Voltage i_D, DRAIN CURRENT (AMPERES)

Typical Transconductance Vs. Drain Current RDS(on), DRAIN-TO-SOURCE ON RESISTANCE (NORMALIZED) V₀₅≠10V



TJ, JUNCTION TEMPERATURE (°C)
Breakdown Voltage Vs. Temperature

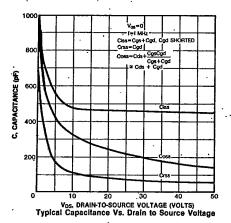
0 40 80 120
T., JUNCTION TEMPERATURE (°C)
Normalized On-Resistance Vs. Temperature

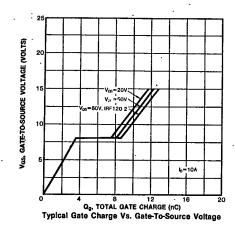
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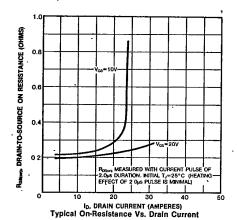
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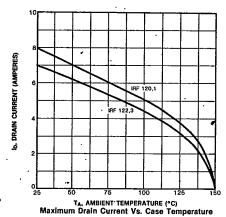
POWER MOSFETS

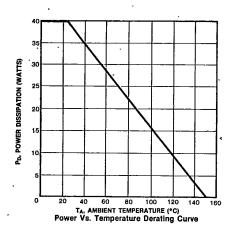
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